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Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A method for hermetically packaging a bulk acoustic resonator device including the steps of:

providing a first wafer having a first surface and a second surface that face toward opposite directions, with a plurality of bulk acoustic resonator devices disposed on the first surface, the first wafer further having a plurality of cavities that are formed at positions corresponding to the bulk acoustic resonator devices and are open at the second surface;

providing a second wafer having a plurality of wells;

providing a third wafer;

bonding the second wafer to the first surface of the first wafer and bonding the third wafer to the second surface of the first wafer to form a composite wafer in which the bulk acoustic resonator devices of the first wafer are aligned with the wells of the second wafer and sealed by the second wafer, and the cavities of the first wafer are sealed by the third wafer; and

forming holes in the composite wafer after formation of the composite wafer so that the holes reach metal tracks connected to the bulk acoustic resonator devices, and filling the holes with metal; and

separating individual bulk acoustic resonator devices by sawing the composite wafer.

2. (Previously Presented) A method as claimed in claim 1, wherein each of the bulk acoustic resonator devices comprises a piezoelectric layer sandwiched between two metal electrodes.

3. (Canceled)